

Comment	Description	Designator	Footprint	LibRef	Quantity	Manufacturer
TIDA-01617	Printed Circuit Board				1	Any
Printed Circuit Board	Printed Circuit Board	!PCB		PCB	1	Any
GRM21BR71A106KE5 1K	CAP, CERM, 10 µF, 10 V,+/- 10%, X7R, 0805	C1, C3, C4	0805_HV	GRM21BR71A106KE5 1K	3	MuRata
GRM185C80J105KE2 6D	CAP, CERM, 1 µF, 6.3 V,+/- 10%, X6S, 0603	C2, C5	0603	GRM185C80J105KE2 6D	2	MuRata
BZV55C15-TP	Diode, Zener, 15 V, 500 mW, MiniMELF	D1	MiniMELF	BZV55C15-TP	1	Micro Commercial Components
Fiducial	Fiducial mark. There is nothing to buy or mount.	FID1, FID2, FID3	Fiducial10-20	Fiducial	3	N/A
NY PMS 440 0025 PH	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	H1, H2, H3, H4	NY PMS 440 0025 PH	NY PMS 440 0025 PH	4	B&F Fastener Supply
1902C	Standoff, Hex, 0.5"L #4-40 Nylon	H5, H6, H7, H8	Keystone_1902C	1902C	4	Keystone
SJ-5303 (CLEAR)	Bumpon, Hemisphere, 0.44 X 0.20, Clear	H9, H10, H11, H12	Bumpon_SJ5003Tran sparent	SJ-5303 (CLEAR)	4	3M
SSQ-110-03-T-D	Receptacle, 2.54mm, 10x2, Tin, TH	J1&J3, J2&4	Samtec_SSQ-110-03- x-D	SSQ-110-03-T-D	2	Samtec
TSW-108-07-G-S	Header, 100mil, 8x1, Gold, TH	J1_1, J1_2(pin number + 8), J2_1, J2_2(pin number + 8), J3_1, J3_2(pin number + 8), J4_1, J4_2(pin number + 8)	TSW-108-07-G-S	TSW-108-07-G-S	8	Samtec
TSW-104-07-G-S	Header, 100mil, 4x1, Gold, TH	J5, J6, J8	TSW-104-07-G-S	TSW-104-07-G-S	3	Samtec
HTSW-103-07-G-D	Header, 2.54mm, 3x2, Gold, TH	J7	Samtec_HTSW-103- 07-x-D	HTSW-103-07-G-D	1	Samtec
Size: 0.65" x 0.20 "	Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	LBL1	Label_650x200	THT-14-423-10	1	Brady
RT0805BRD0710K6L	RES, 10.6 k, 0.1%, 0.125 W, 0805	R1	0805_HV	RT0805BRD0710K6L	1	Yageo America
RT0805BRD075K3L	RES, 5.30 k, 0.1%, 0.125 W, 0805	R2	0805_HV	RT0805BRD075K3L	1	Yageo America
RT0805BRD073K52L	RES, 3.52 k, 0.1%, 0.125 W, 0805	R3	0805_HV	RT0805BRD073K52L	1	Yageo America
RT0603DRE07100RL	RES, 100, 0.5%, 0.1 W, 0603	R8, R9, R10, R11, R12, R13, R14, R15, R16, R17, R18, R19, R20, R21, R22, R23	0603	RT0603DRE07100RL	16	Yageo America
5010	Test Point, Multipurpose, Red, TH	TP1 LAT, TP2 SCLK, TP3 SIN, TP4 BLANK, TP5 VCC, TP6 IREF, TP7 GND, TP8 VLED	Keystone5010	5010	8	Keystone

Used in BOM report		U1, U2, U3, U4, U5, U6, U7, U8	APM4953	APM4953	8	Used in BOM report
TLC59282DBQ	16-Channel Constant Current LED Driver with 4-Channel Grouped Delay, 3 to 5.5 V, -40 to 85 degC, 24-pin SOP (DBQ24), Green (RoHS & no Sb/Br)	U9	DBQ0024A_N	TLC59282DBQ	1	Texas Instruments

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